

METHODS AND APPARATUS FOR VARIABLE LATENCY SUPPORT

Abstract of the Disclosure

5 Methods and apparatus are provided for interconnecting primary components
with secondary components on a programmable chip. Control, data, and address lines
are automatically generated to connect primary components and secondary
components with an interconnection module. The interconnection connection module
manages interaction between primary components and secondary components and
10 provides support for fixed latency and variable latency secondary components.